

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package name	Standard dimensions mm (inch)
1	CN1	1	–	XG8W-1431	Omron	Terminal, 300 V, 3 A	–	–
2	CN2	1	–	XG4C-1631	Omron	Terminal, 250 V, 1 A	–	–
3	CN3	1	–	WR-60P-HF-HD-A1E	JAE	Terminal, 200 V, 0.3 A	–	–
4	CN4	1	–	SM03B-PASS-TBT(LF)(SN)	JST	Terminal, 250 V, 3 A	–	–
5	CN5	1	–	SM02B-PASS-TBT(LF)(SN)	JST	Terminal, 250 V, 3 A	–	–
6	CN6	1	–	SM04B-PASS-TBT(LF)(SN)	JST	Terminal, 250 V, 3 A	–	–
7	CN7	1	–	SM10B-PASS-TBT(LF)(SN)	JST	Terminal, 250 V, 3 A	–	–
8	C1, C5, C6, C7, C17, C83	6	0.1 μ F			Ceramic, 6.3 V, \pm 15 %	1005	1.0 x 0.5 (0402)
9	C2, C4	2	1000 pF			Ceramic, 16 V, \pm 15 %	1608	1.6 x 0.8 (0603)
10	C8, C9, C10, C11, C12, C13, C14, C15, C16, C18, C20, C21, C22, C23, C24, C25, C26, C27, C28, C29, C30, C31, C32, C33, C34, C35, C36, C37, C38, C39, C40, C41, C42, C43, C44, C45, C46, C47, C48, C49, C50, C51, C52, C53, C85, C86, C89, C90, C96, C97	50	1 μ F			Ceramic, 10 V, \pm 10 %	1608	1.6 x 0.8 (0603)
11	C19, C79, C81, C82, C84, C87, C88, C92, C93, C94	10	10 μ F			Ceramic, 10 V, \pm 10 %	1608	1.6 x 0.8 (0603)
12	C54, C55, C56, C57, C60, C69, C76, C77, C78, C80, C91, C95	12	0.1 μ F			Ceramic, 50 V, \pm 10 %	1608	1.6 x 0.8 (0603)
13	C58, C59, C61, C62, C67, C68, C70, C71	8	470 pF			Ceramic, 50 V, \pm 5 %	1608	1.6 x 0.8 (0603)
14	C63, C64, C65, C66, C72, C73, C74, C75	8	0.015 μ F			Ceramic, 50 V, \pm 10 %	1608	1.6 x 0.8 (0603)
15	D1, D2, D3, D4, D5, D7, D8, D9, D10, D11, D12, D13, D14, D15, D16, D17, D18, D19, D20, D21, D22, D23, D24	23	45 V	1SS396	TOSHIBA	Schottky Barrier Diode	SOT-346	2.9 x 2.5

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16	D6	1	30 V	CUS05F30	TOSHIBA	Schottky Barrier Diode	SOD-323	2.5 x 1.25
17	FU1, FU2	2	1.6 A			Fuse	–	6.0 x 2.5
18	IC1, IC2	2	–	TPS3897ADRY	Texas Instruments	Adjustable Voltage Monitor	SON	1.2 x 1.65
19	IC3	1	–	TMS320F28377SPTP	Texas Instruments	32-bit Microcontrollers-MCU Soprano	HLQFP	24 x 24
20	IC4	1	512 Kbit	24LC512-I/SM	Atmel	EEPROM	SOIJ	5.21 x 5.28
21	IC5, IC6, IC7	3	–	74VHCT540AFT	TOSHIBA	Buffer	TSSOP 20B	6.5 x 6.4
22	IC8, IC13, IC14	3	–	TC7SH17F	TOSHIBA	Single Schmitt Buffer	SOT-25	2.9x2.8
23	IC9, IC10	2	–	OPA4322AIPWR	Texas Instruments	Operational amplifier	TSSOP-14	6.9x5.6
24	IC11	1	–	TC74VHC540FT	TOSHIBA	Buffer	TSSOP	6.9 x 4.4
25	IC12	1	–	TCAN332D	Texas Instruments	CAN Transceivers	SOIC	5.0 x 3.9
26	IC15	1	–	REF2030AIDDCT	Texas Instruments	Voltage References	SOT-23-THIN	3.05 x 3.05
27	LED1	1	–	VCDG1111C-4BY3C-TR	STANLEY	LED	TSSOP 20B	6.5 x 6.4
28	L1	1	–	MMZ2012S601AT000	TDK	Chip beads	2012	2.0 x 1.2 (0805)
29	PS1	1	3.3 V 1.5 A	TCR15AG33	TOSHIBA	Regulator	WCSP6F	1.2 x 0.8
30	PS2	1	1.2 V 1.5 A	TCR15AG12	TOSHIBA	Regulator	WCSP6F	1.2 x 0.8
31	R1 ,R12, R13, R20, R21	5	4.7 kΩ			100 mW, ±1 %	1608	1.6 x 0.8 (0603)
32	R2	1	300 kΩ			100 mW, ±0.1 %	1608	1.6 x 0.8 (0603)
33	R3, R17, R22, R23, R24, R25, R26	7	100 kΩ			100 mW, ±1 %	1608	1.6 x 0.8 (0603)
34	R4	1	56 kΩ			100 mW, ±0.1 %	1608	1.6 x 0.8 (0603)
35	R5, R7, R15, R16, R30, R31, R32, R33, R34, R35, R36, R37, R38, R39, R40, R41, R42, R43, R44, R45, R46, R47, R48, R49, R50, R51, R54, R55, R62, R63, R66, R67, R74, R75, R76, R77, R78, R79, R80, R82, R83, R84, R86, R88, R89, R90, R91, R92, R93, R94, R95	51	10 kΩ			100 mW, ±1 %	1608	1.6 x 0.8 (0603)

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package name	Standard dimensions mm (inch)
36	R6	1	130 kΩ			100 mW, ±1 %	1608	1.6 x 0.8 (0603)
37	R11, R85, R87, R96, R97, R98, R99, R100, R101, R102, R103	11	100 Ω			100 mW, ±1 %	1608	1.6 x 0.8 (0603)
38	R14, R28, R29	3	2.2 kΩ			100 mW, ±1 %	1608	1.6 x 0.8 (0603)
39	R18	1	0 Ω			1 A	1608	1.6 x 0.8 (0603)
40	R52, R53, R56, R57, R64, R65, R68, R69	8	15 kΩ			100 mW, ±1 %	1608	1.6 x 0.8 (0603)
41	R58, R59, R60, R61, R70, R71, R72, R73	8	33 Ω			100 mW, ±1 %	1608	1.6 x 0.8 (0603)
42	R81	1	470 Ω			100 mW, ±1 %	1608	1.6 x 0.8 (0603)
43	SW1	1	–	SKRKAEE010	ALPS	Tact Switch	-	4.8 x 2.9
44	SW2	1	–	A6H-2102	Omron	Slide DIP Switch	-	3.77 x 4.5
45	TP1, TP2, TP3, TP4, TP5, TP6, TP7, TP8, TP9, TP10, TP11, TP12, TP13, TP14, TP24, TP25	16	–	HK-3-G	MAC8	Test Pin	-	2.0 x 1.3
46	X1	1	–	ASEMB-20.000MHZ-XY-T	Abracon	Clock Oscillators	QFN	3.2 x 2.5

Not Mounted Items

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package name	Standard dimensions mm (inch)	Not Mounted
901	C3	1	–	–	–	–	1608	1.6 x 0.8 (0603)	Not Mounted
902	R8, R9, R10, R19	4	–	–	–	–		1.6 x 0.8 (0603)	Not Mounted

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